SKM1000GB17R8

SEMITRANS® 10

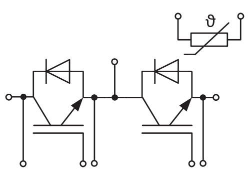
SKM1000GB17R8

Features

- Symmetrical current sharing
- Low-inductive module design
- High mechanical robustness
- UL recognized, file no. E63532

Typical Applications*

- Motor Drives
- UPS Systems
- Solar Inverters



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Absolute Maximum Ratings				
Symbol	**Conditions**		**Values**	**Unit**
IGBT				
V_{CES}	T_j = 25 °C		1700	V
I_C	T_j = 175 °C	T_c = 25 °C	1574	A
		T_c = 100 °C	1027	A
I_{Cnom}			1000	A
I_{CRM}	I_{CRM} = 2xI_{Cnom}		2000	A
V_{GES}			-20 ... 20	V
t_{psc}	V_{CC} = 1200 V $V_{GE} \leq$ 15 V $V_{CES} \leq$ 1700 V	T_j = 150 °C	10	µs
T_j			-40 ... 175	°C
Inverse diode				
V_{RRM}	T_j = 25 °C		1700	V
I_F	T_j = 175 °C	T_c = 25 °C	1449	A
		T_c = 100 °C	905	A
I_{Fnom}			1000	A
I_{FRM}	I_{FRM} = 2xI_{Fnom}		2000	A
I_{FSM}	t_p = 10 ms, sin 180°, T_j = 25 °C		6240	A
T_j			-40 ... 175	°C
Module				
T_{stg}			-40 ... 150	°C
V_{isol}	AC sinus 50 Hz, t = 1 min		4000	V

Characteristics						
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
IGBT						
$V_{CE(sat)}$	I_C = 1000 A V_{GE} = 15 V chiplevel	T_j = 25 °C		1.66	1.99	V
		T_j = 150 °C		2.01	2.33	V
V_{CE0}	chiplevel	T_j = 25 °C		1.06	1.12	V
		T_j = 150 °C		0.95	1.05	V
r_{CE}	V_{GE} = 15 V chiplevel	T_j = 25 °C		0.60	0.87	mΩ
		T_j = 150 °C		1.06	1.28	mΩ
$V_{GE(th)}$	V_{GE}=V_{CE}, I_C = 36 mA		5	5.8	6.5	V
I_{CES}	V_{GE} = 0 V, V_{CE} = 1700 V, T_j = 25 °C				6.0	mA
C_{ies}	V_{CE} = 25 V V_{GE} = 0 V	f = 1 MHz		90.0		nF
C_{oes}		f = 1 MHz		3.00		nF
C_{res}		f = 1 MHz		0.24		nF
Q_G	V_{GE} = -15V/+15V			5640		nC
R_{Gint}	T_j = 25 °C			1.8		Ω
$t_{d(on)}$	V_{CC} = 900 V I_C = 1000 A V_{GE} = +15/-15 V $R_{G\ on}$ = 0.7 Ω $R_{G\ off}$ = 0.7 Ω di/dt$_{on}$ = 7.8 kA/µs di/dt$_{off}$ = 4.8 kA/µs du/dt = 4600 V/µs L_s = 24 nH	T_j = 150 °C		476		ns
t_r		T_j = 150 °C		105		ns
E_{on}		T_j = 150 °C		465		mJ
$t_{d(off)}$		T_j = 150 °C		713		ns
t_f		T_j = 150 °C		158		ns
E_{off}		T_j = 150 °C		332		mJ
$R_{th(j-c)}$	per IGBT				0.03	K/W
$R_{th(c-s)}$	per IGBT (λ_{grease}=0.81 W/(m*K))			0.0155		K/W

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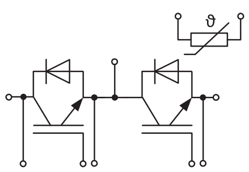

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Symbol	Conditions		min.	typ.	max.	Unit
Inverse diode						
$V_F = V_{EC}$	I_F = 1000 A, V_{GE} = 0 V, chiplevel	T_j = 25 °C		1.78	2.12	V
		T_j = 150 °C		1.81	2.14	V
V_{F0}	chiplevel	T_j = 25 °C		1.32	1.56	V
		T_j = 150 °C		1.08	1.22	V
r_F	chiplevel	T_j = 25 °C		0.46	0.56	mΩ
		T_j = 150 °C		0.73	0.92	mΩ
I_{RRM}	I_F = 1000 A, di/dt_{off} = 6.6 kA/µs, V_{GE} = ±15 V, V_{CC} = 900 V	T_j = 150 °C		711		A
Q_{rr}		T_j = 150 °C		325		µC
E_{rr}		T_j = 150 °C		159		mJ
$R_{th(j-c)}$	per diode				0.042	K/W
$R_{th(c-s)}$	per diode (λ_{grease}=0.81 W/(m*K))			0.0165		K/W
Module						
L_{CE}				10		nH
$R_{CC'+EE'}$	measured per switch, T_C = 25 °C			0.2		mΩ
$Rth_{(c-s)1}$	calculated without thermal coupling (λ_{grease}=0.81 W/(m*K))			0.0040		K/W
$Rth_{(c-s)2}$	including thermal coupling, Ts underneath module (λ_{grease}=0.81 W/(m*K))			0.006		K/W
M_s	to heat sink M5		4		6	Nm
M_t		to terminals M8	8		10	Nm
		to terminals M4	1.8		2.1	Nm
w					1250	g
Temperature Sensor						
R_{100}	T_c=100°C (R_{25}=5 kΩ)			493 ± 5%		Ω
$B_{100/125}$	$R_{(T)}=R_{100}exp[B_{100/125}(1/T-1/T_{100})]$; T[K];			3550 ±2%		K

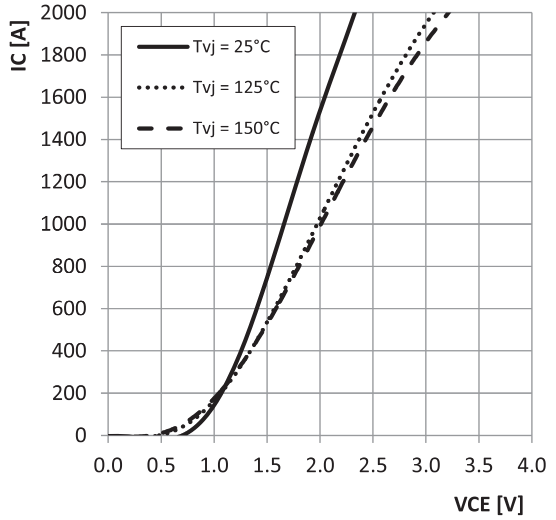


Fig. 1: Output Characteristics IGBT (typical); $I_C = f(V_{CE})$; $V_{GE} = 15V$

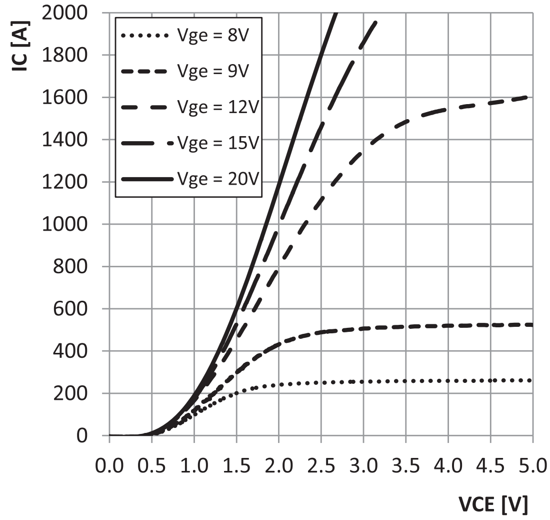


Fig. 2: Output Characteristics IGBT (typical); $I_C = f(V_{CE})$; $T_j = 150$ °C

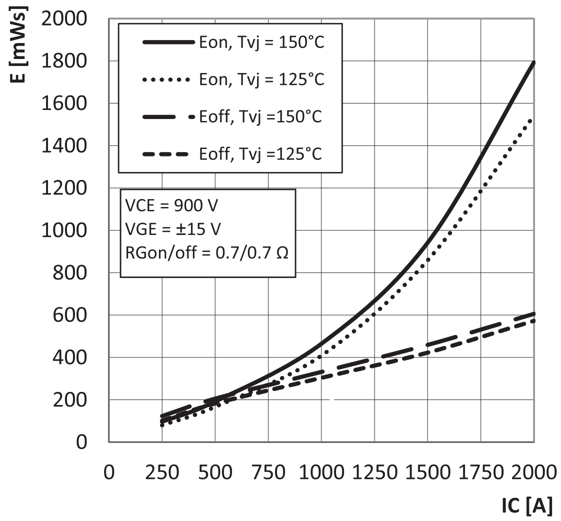


Fig. 3: Switching losses IGBT (typical) $E=f(I_C)$

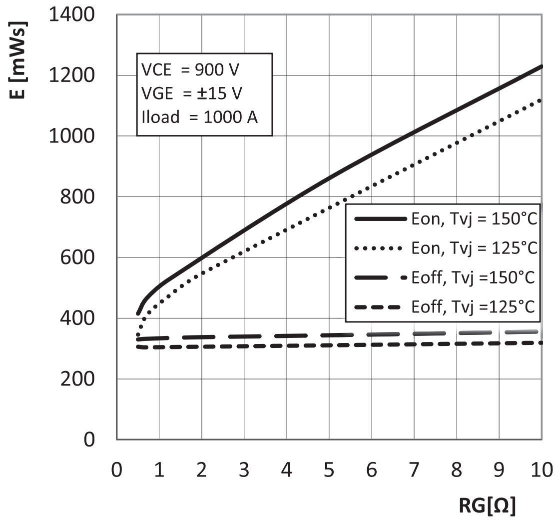


Fig. 4: Switching losses IGBT (typical) $E=f(R_G)$

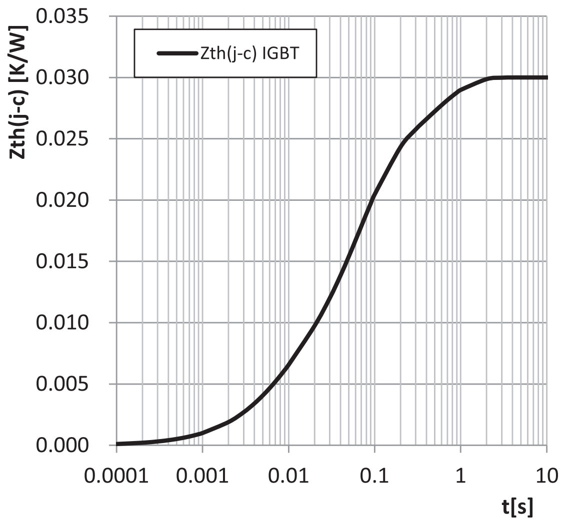


Fig. 5: Transient thermal impedance IGBT

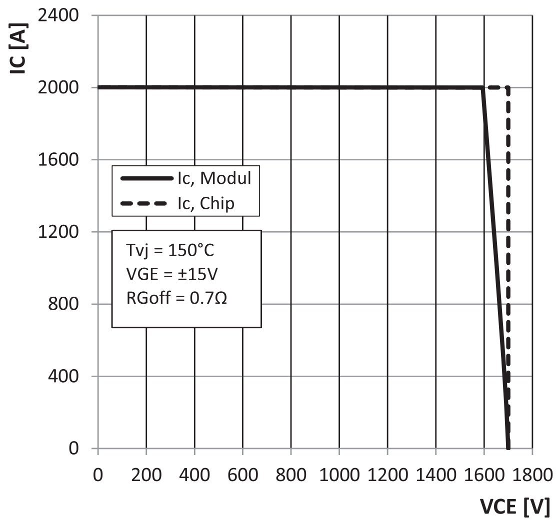


Fig. 6: RBSOA IGBT

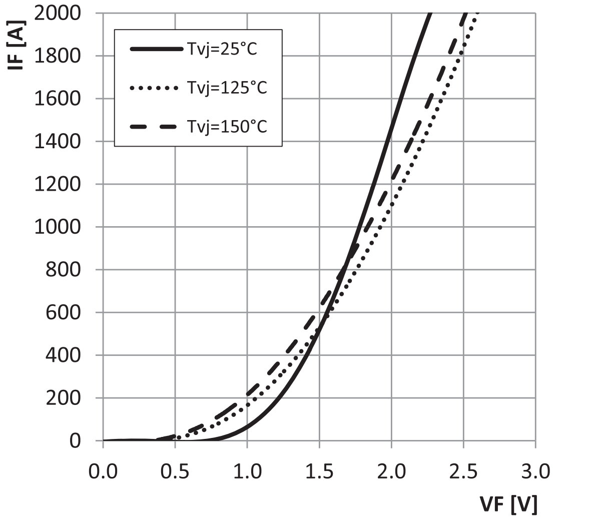


Fig. 7: Forward characteristics Diode (typical); $I_F=f(V_F)$

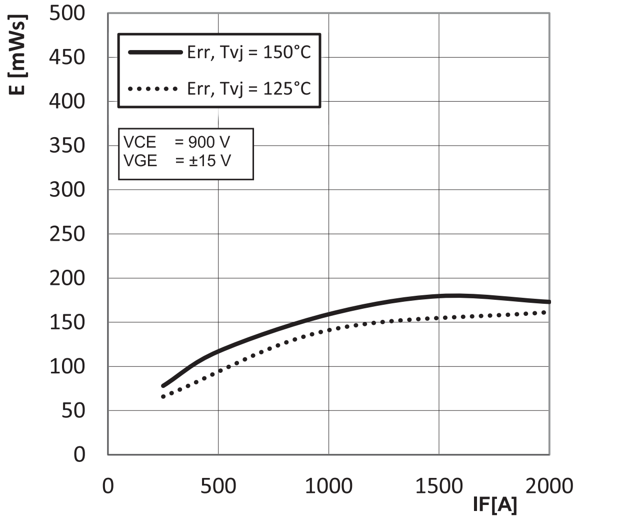


Fig. 8: Switching losses Diode (typical) $E=f(I_F)$

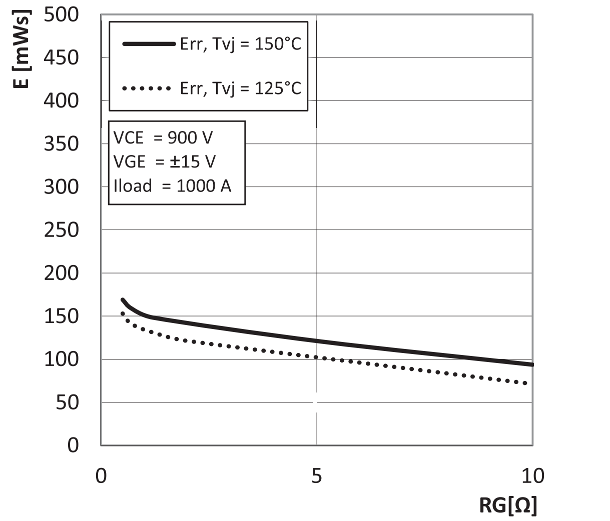


Fig. 9: Switching losses Diode (typical) $E=f(R_G)$

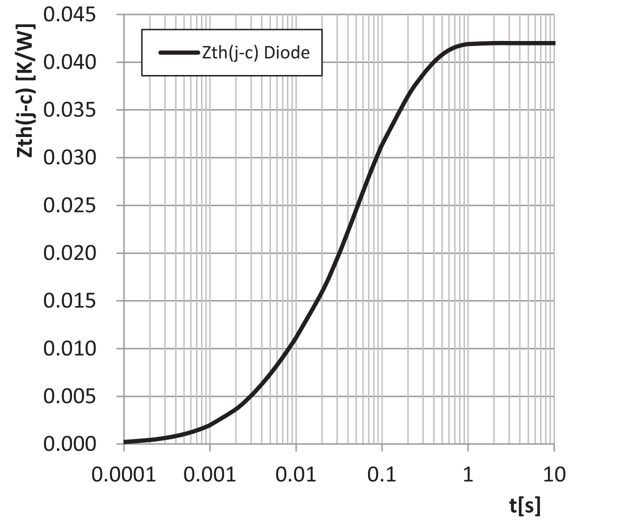


Fig. 10: Transient thermal impedance Diode

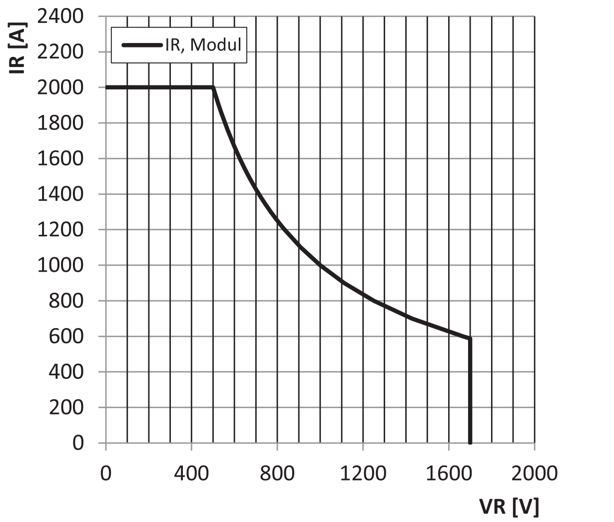


Fig. 11: SOA Diode

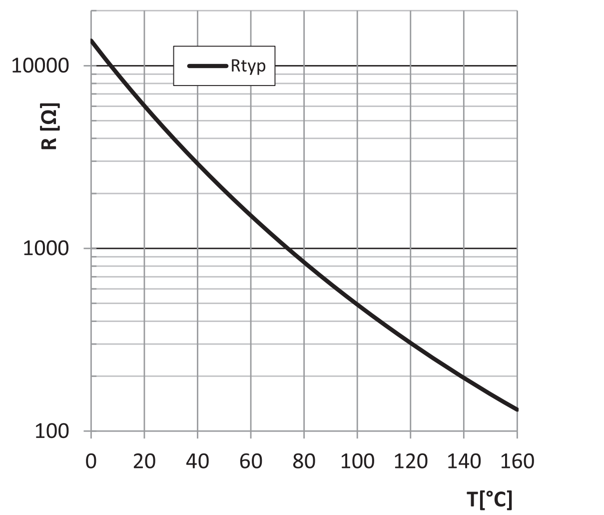
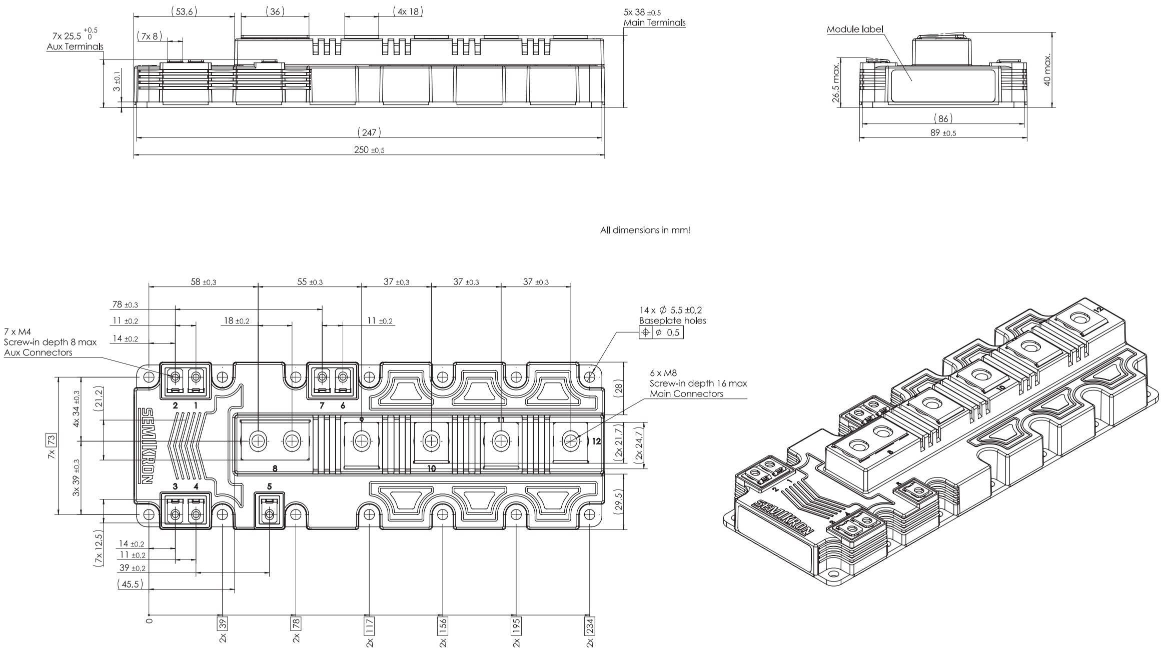
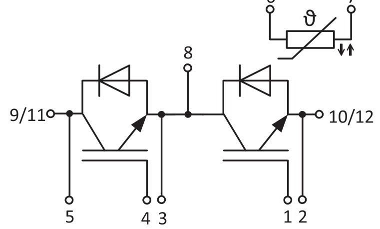


Fig. 12: NTC characteristics (typical)


All dimensions in mm!
Module label
Main Terminals
Aux Terminals
Baseplate holes
Main Connectors
Aux Connectors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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

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